



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

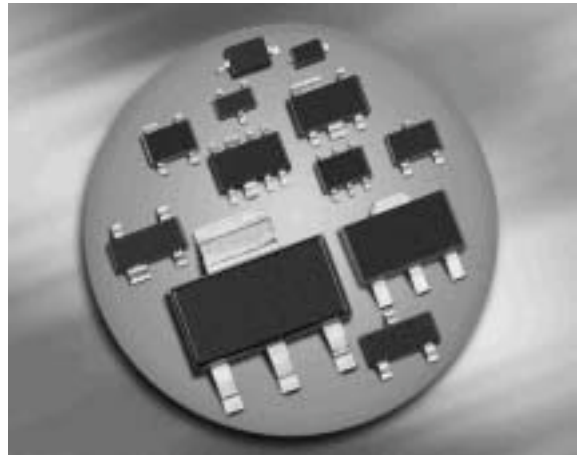
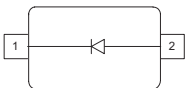
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



Medium Power AF Schottky Diode

- Forward current: 1 A
- Reverse voltage: 30 V
- Very low forward voltage
(typ. 0.41V @ $I_F = 1A$)
- For high efficiency DC/DC conversion,
fast switching, protection and
clamping applications
- Pb-free (RoHS compliant) package¹⁾
- Qualified according AEC Q101


BAS 3010A-03W


Type	Package	Configuration	Marking
BAS3010A-03W	SOD323	single	4/ blue

Maximum Ratings at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Value	Unit
Diode reverse voltage ²⁾	V_R	30	V
Forward current ²⁾	I_F	1	A
Average rectified forward current (50/60Hz, sinus)	I_{FAV}	1	
Repetitive peak forward current ($t_p \leq 1 \text{ ms}$, $D \leq 0.5$)	I_{FRM}	3.5	
Non-repetitive peak surge forward current ($t \leq 10\text{ms}$)	I_{FSM}	10	
Junction temperature	T_j	150	$^\circ\text{C}$
Operating temperature range	T_{op}	-65 ... 125	
Storage temperature	T_{stg}	-65 ... 150	

¹⁾Pb-containing package may be available upon special request

²⁾For $T_A > 25^\circ\text{C}$ the derating of V_R and I_F has to be considered. Please refer to the attached curves.

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ¹⁾	R_{thJS}	≤ 82	K/W

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	

DC Characteristics

Reverse current ²⁾	I_R				μA
$V_R = 5\text{ V}$		-	5	25	
$V_R = 10\text{ V}$		-	10	50	
$V_R = 30\text{ V}$		-	40	200	
Forward voltage ²⁾	V_F				mV
$I_F = 1\text{ mA}$		-	170	220	
$I_F = 10\text{ mA}$		-	220	270	
$I_F = 100\text{ mA}$		-	290	340	
$I_F = 500\text{ mA}$		-	350	410	
$I_F = 1\text{ A}$		-	410	470	

AC Characteristics

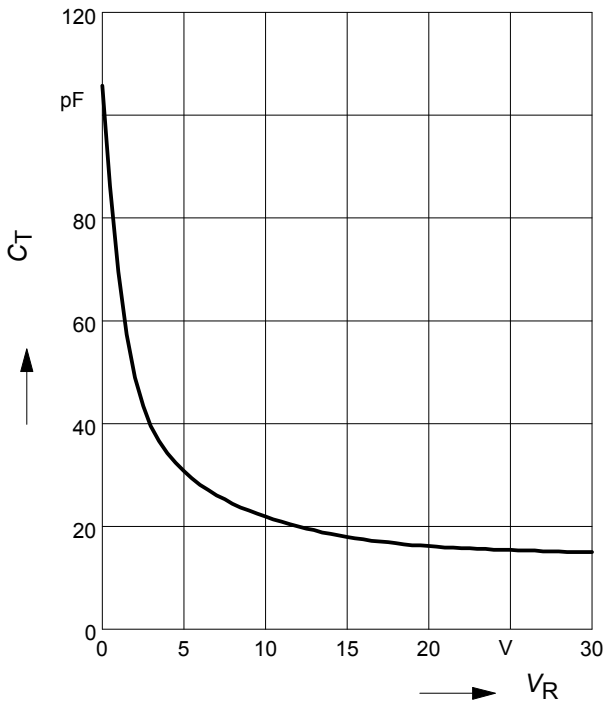
Diode capacitance	C_T	-	28	35	pF
$V_R = 5\text{ V}, f = 1\text{ MHz}$					

¹For calculation of R_{thJA} please refer to Application Note Thermal Resistance

²Pulsed test: $t_p = 300\ \mu\text{s}$; $D = 0.01$

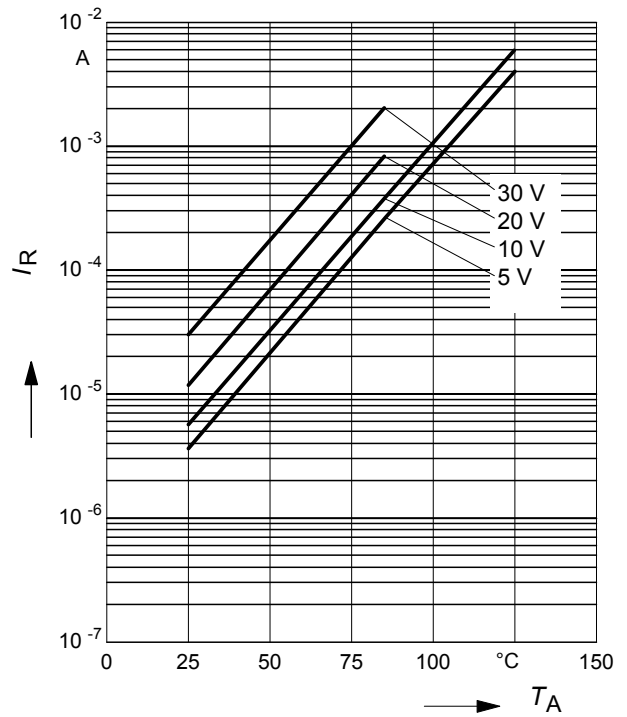
Diode capacitance $C_T = f(V_R)$

$f = 1\text{MHz}$



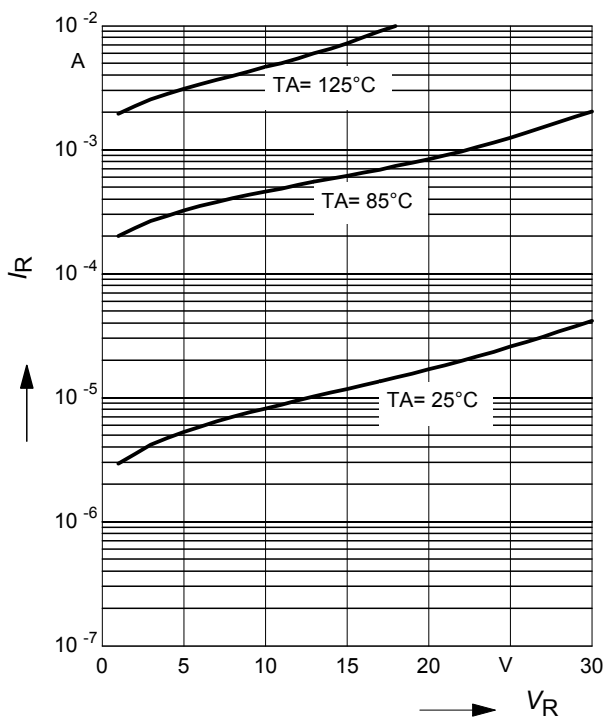
Reverse current $I_R = f(T_A)$

$V_R = \text{Parameter}$



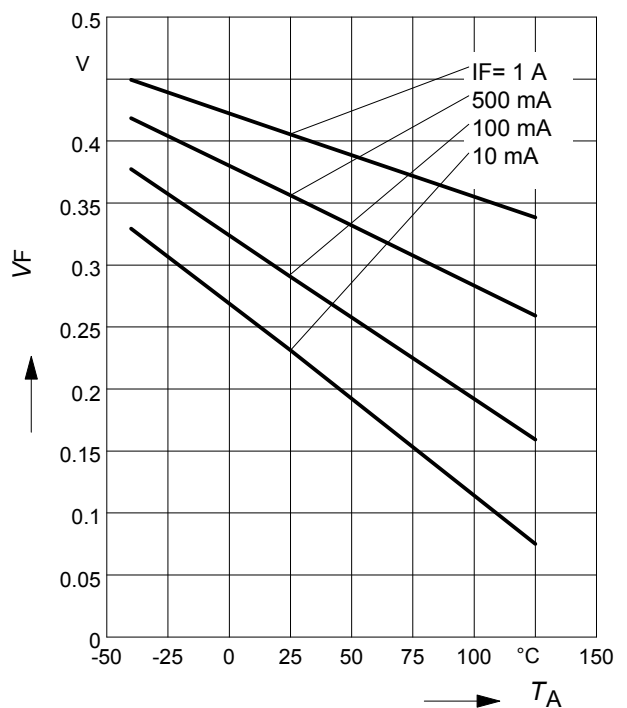
Reverse current $I_R = f(V_R)$

$T_A = \text{Parameter}$



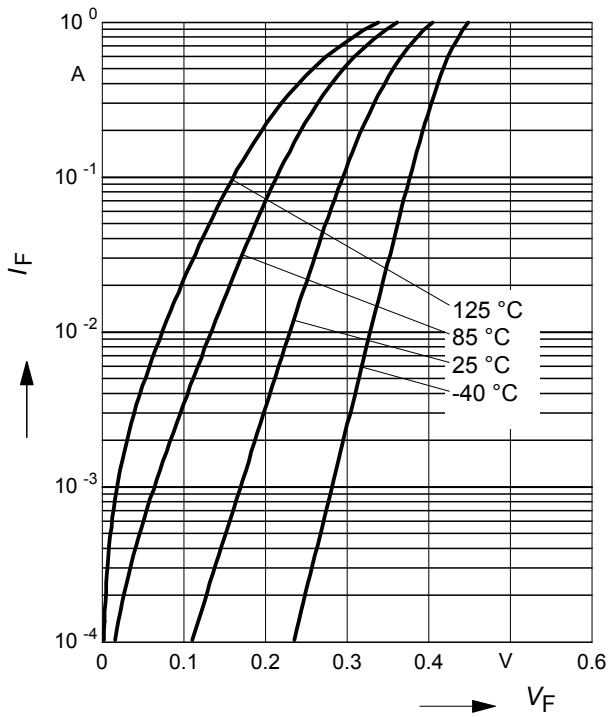
Forward Voltage $V_F = f(T_A)$

$I_F = \text{Parameter}$



Forward current $I_F = f(V_F)$

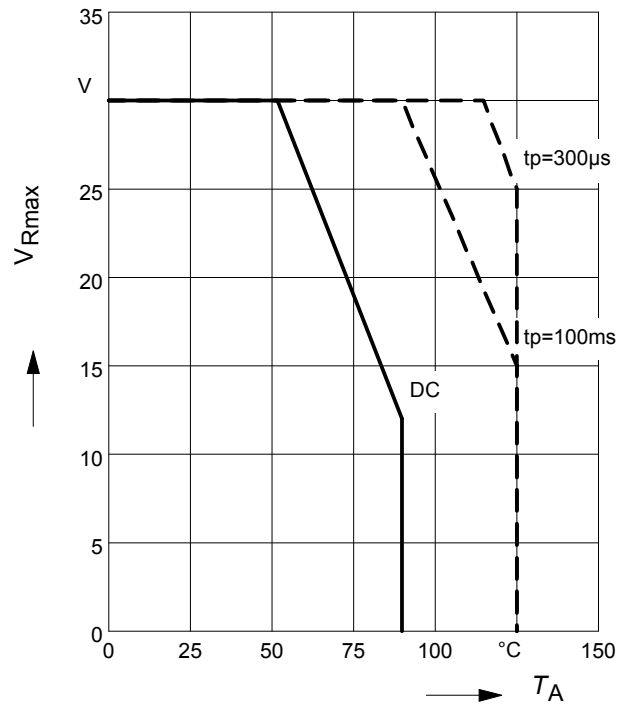
T_A = Parameter



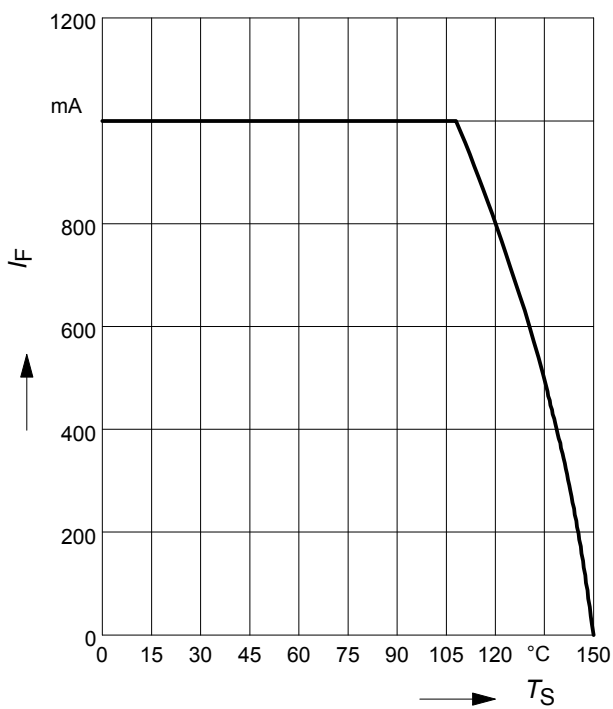
Permissible Reverse voltage $V_R = f(T_A)$

t_p = Parameter, Duty cycle < 0.01

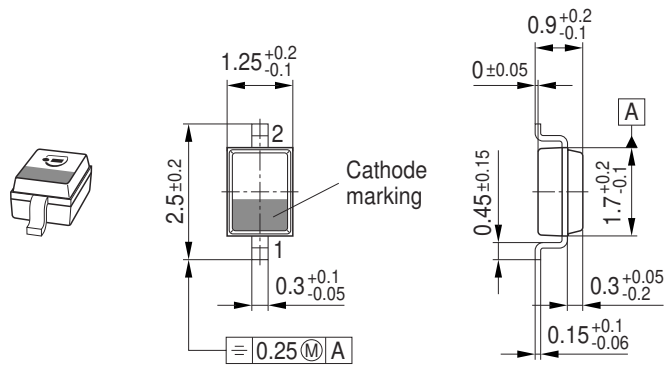
Device mounted on PCB with $R_{th} = 160$ k/W



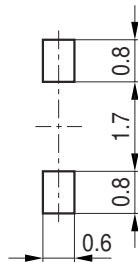
Forward current $I_F = f(T_S)$



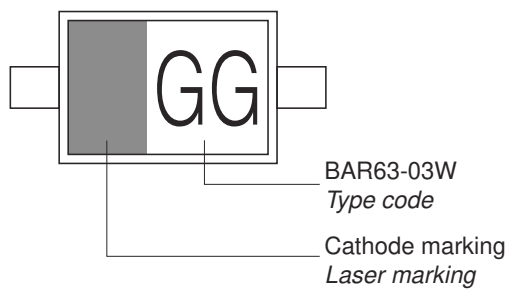
Package Outline



Foot Print

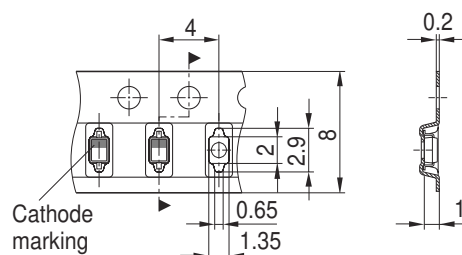


Marking Layout (Example)



Standard Packing

Reel \varnothing 180 mm = 3.000 Pieces/Reel
 Reel \varnothing 330 mm = 10.000 Pieces/Reel



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